

# The OBELIX Chip for the Belle II VTX Upgrade

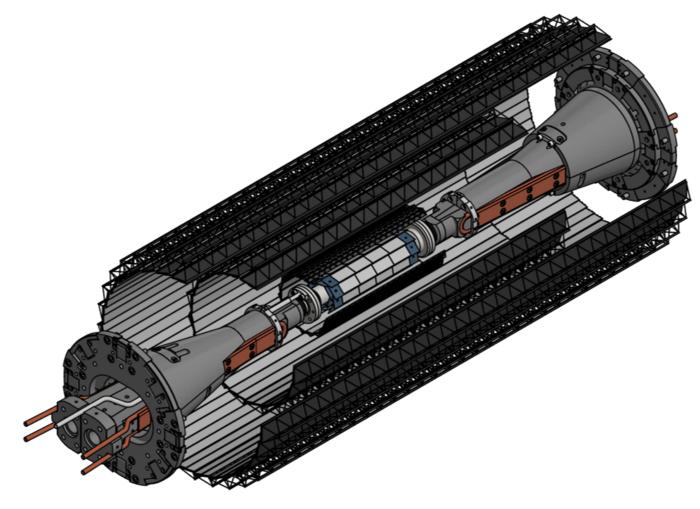
Maximilian Babeluk on behalf of the VTX Upgrade Group

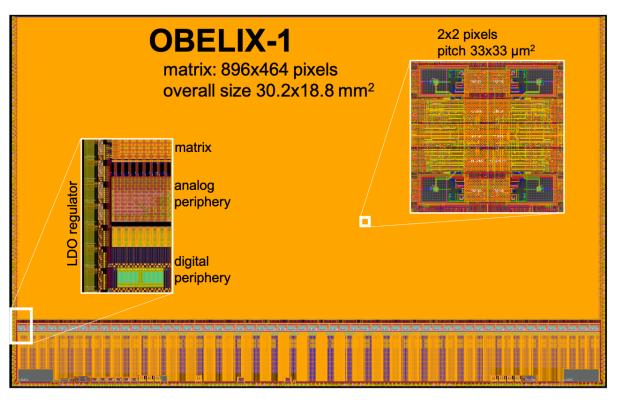


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# The VTX Upgrade

- Opportunity to upgrade the Belle II Vertex Detector during Long Shutdown 2 (Around 2028)
- Interaction region is likely upgraded: Rework of the Vertex Detector necessary
- Improves tracking performance at increased beam background due to luminosity increase
- Five layers with the same DMAPS sensor: The OBELIX (**O**ptimized **BEL**le II p**IX**el) Chip
- Fully pixelated design for low occupancy and fake-rate at high hitrates
- iVTX (2 inner layers): Self supported, air cooled, all silicon ladders, with redistribution layer
- oVTX (3 outer layers): Carbon fiber support, liquid cooled
- See Talk from G. Rizzo on Tuesday





## **The OBELIX Chip**

- Matrix inherited from TJ-Monopix2
- 464 rows and 896 columns
- Timestamp period: 47 ns
- Up to 10  $\mu$ s trigger latency
- Power:  $< 200 \text{ mW/cm}^2$
- TID tolerance: 1 MGy
- NIEL tolerance:  $5 \times 10^{14} \, n_{eq}/cm^2$
- Hitrates up to  $120 \text{ MHz/cm}^2$
- Supply: 2 to 3 V

### New On-chip features

- Trigger memory
- Precision timing measurement (PTD)
- Transmission for trigger contribution (TTT)

#### **OBELIX-1 Pixel Matrix** 896 Columns, 464 Rows **Analog EoC & Buffers** Temperature Sensors PowerOn Reset IDACs & VDACs Monitoring ADC TRU (Trigger Unit) FRG0 (Trigger Group) TRG1 (Trigger Group) FRG111 (Trigger Group CO EoC1 EoC2 EoC CO EoC1 EoC2 E Stage 1 Memory ... Stage 1 Memory Stage 1 Memory 0 Stage 2 Memory Stage 2 Memor Stage 2 Memory CRU SCU (Sync Clock Unit) (Control Unit) TXU (Transmission Unit) (Track Trigger Transmission)

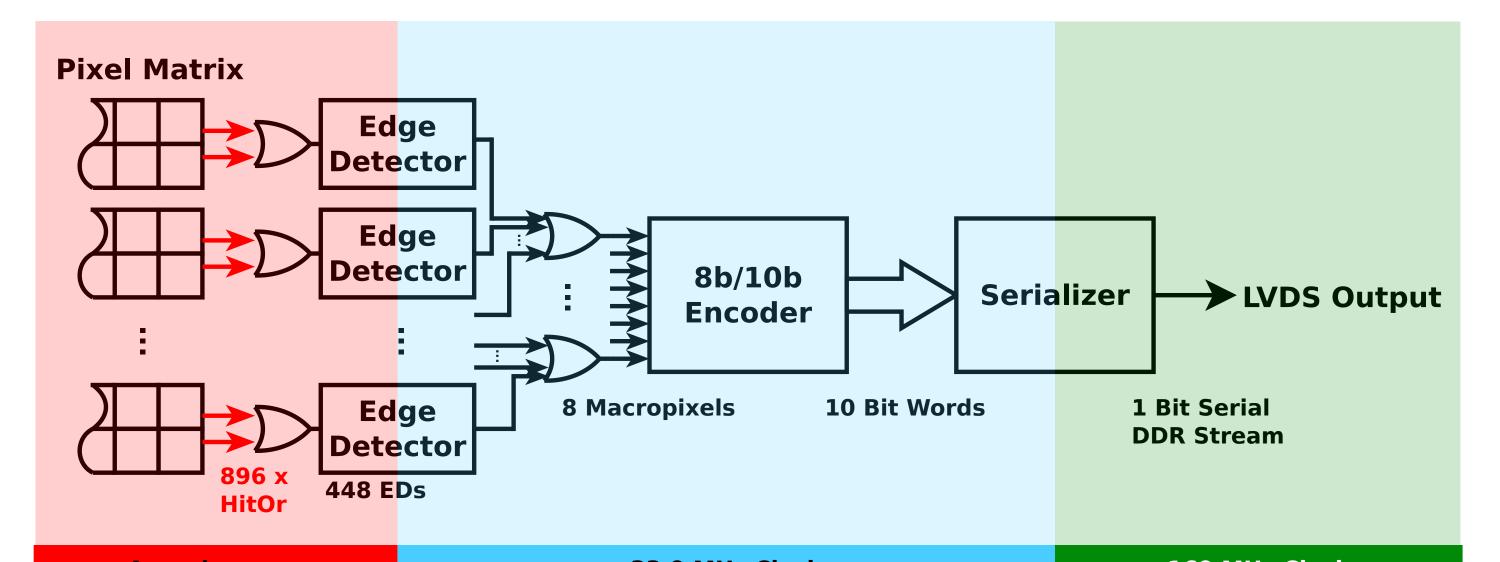
- LDOs for wide supply voltage range
- Several temperature sensors across the chip
- Monitoring ADC for power and temperature

# • OBELIX can contribute to the trigger decision

• This can be used to build a VTX track trigger

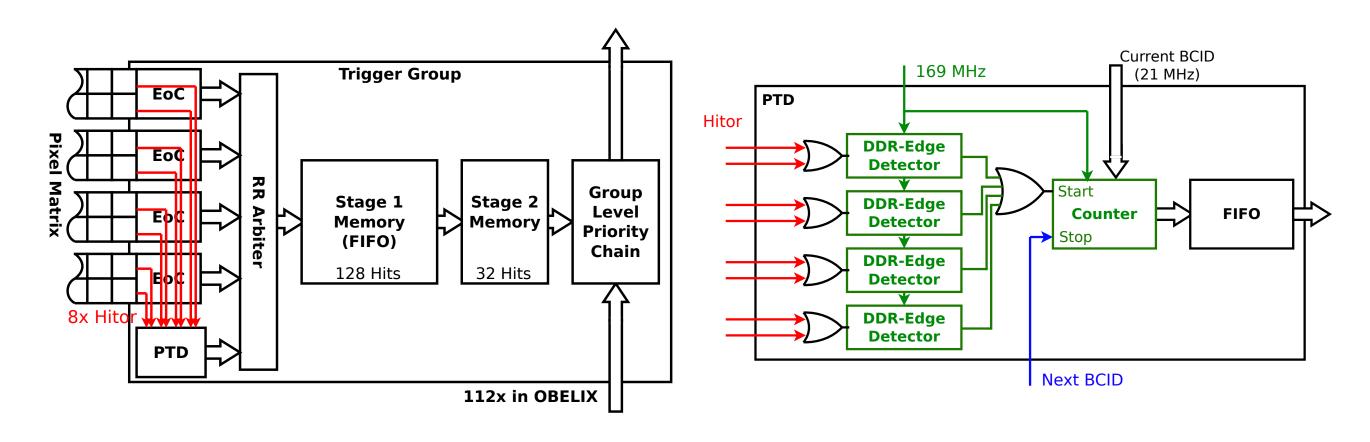
**Track Trigger Transmission (TTT)** 

- Datapath independent from normal readout (extra LVDS line)
- Chip is divided into small number of macropixels (2 to 8 depending on wiring) • Any hit inside a macropixel region activates the macropixel
- Time binning: 29.5 ns, 8b/10b encoded stream, one bit per macropixel • Only enabled in oVTX

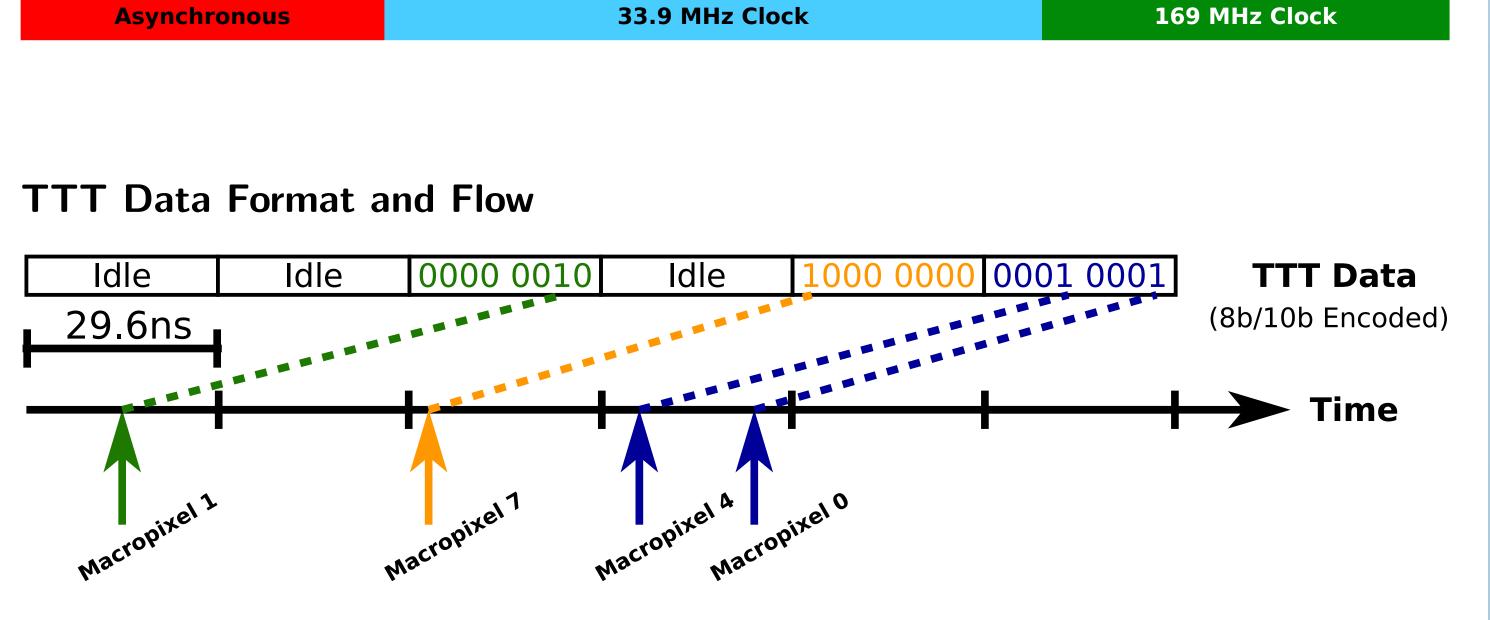


# **Peripheral Time to Digital Converter (PTD)**

- Precision timing feature (enabled via configuration)
- Uses the HitOr lines to measure timing
- HitOr: Discriminator outputs chained via OR-gates along each column
- Timing resolution < 2 ns after calibration from measurements with TJ-Monopix2
- After irradiation (with VTX total design fluence): < 3 ns
- OBELIX: Sampling in the periphery with 3 ns period (196 MHz and DDR)
- Result is injected into datastream
- Association of hit-data with PTD-data (offline)
- Dead-time and not always possible without ambiguities

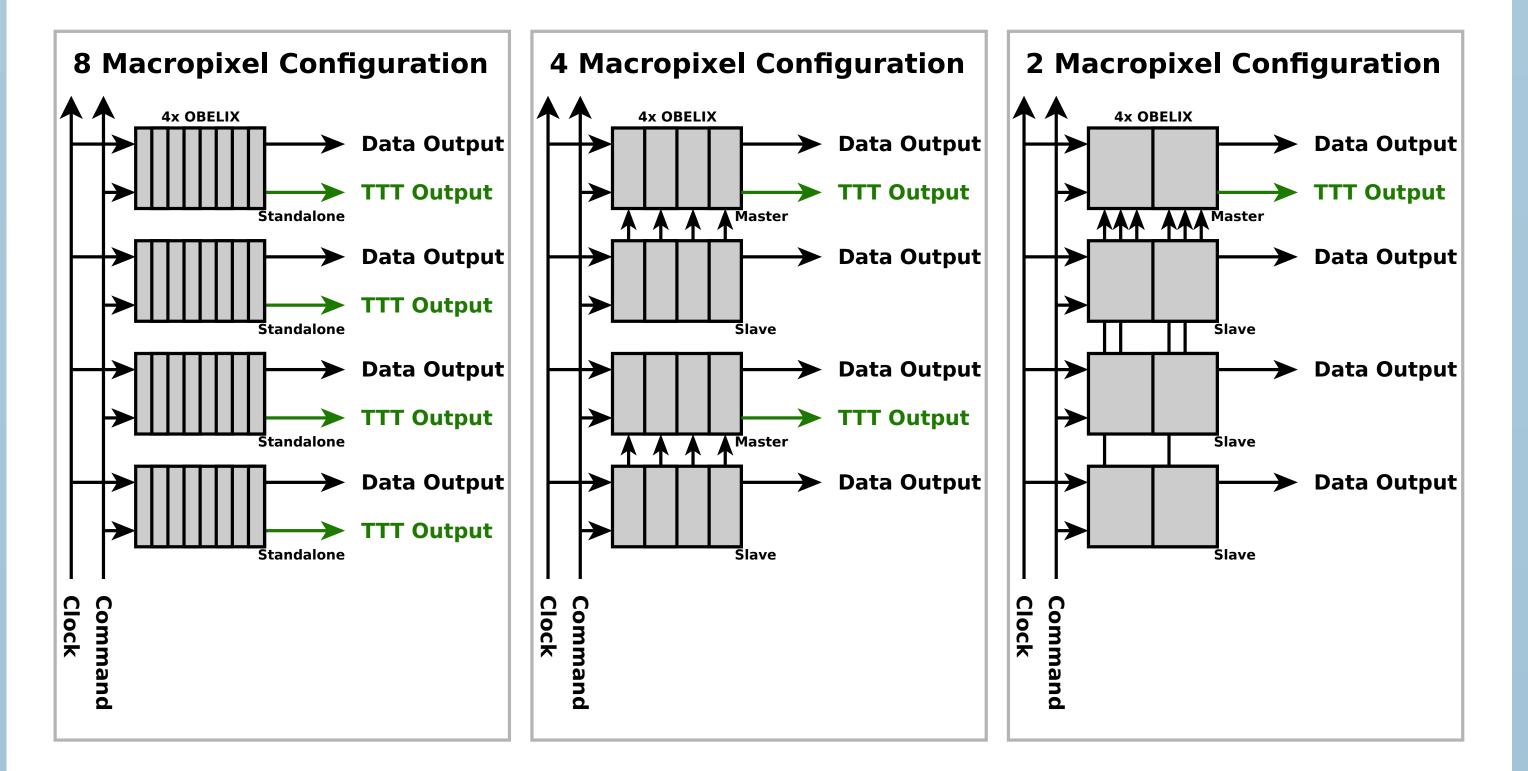


- Design decision: Number of columns per ED
- Impacts performance and power consumption

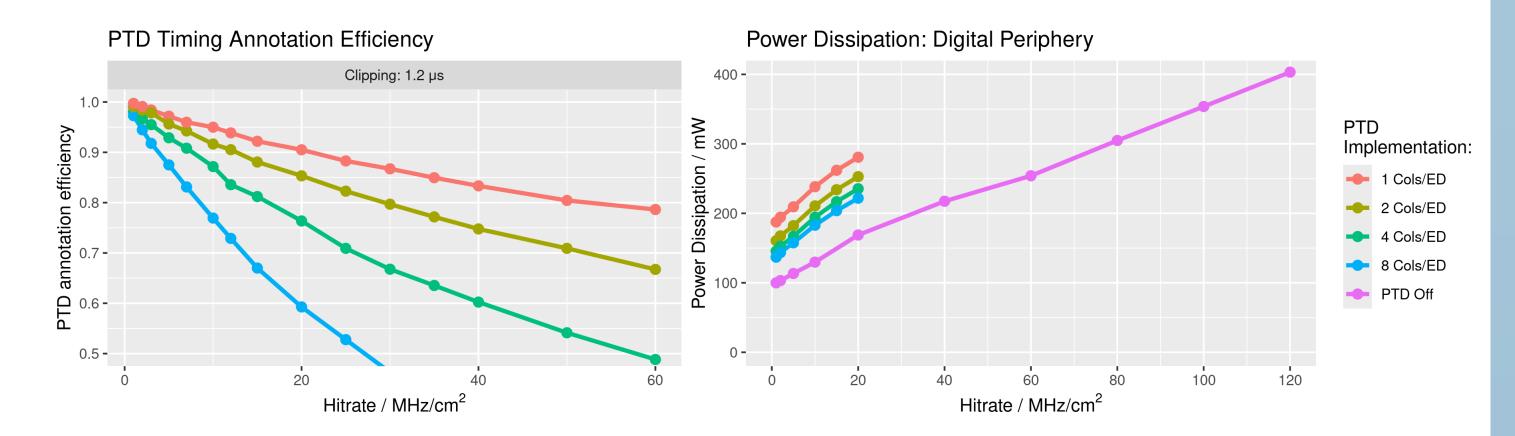


- No frame structure, each byte corresponds to one time-bin
- Each bit in byte corresponds to one macropixel
- Fixed latency (100 ns), high bandwidth
- Synchronization via command input

## **Possible Wiring Configurations**



- Decision depends on power budget consideration of other modules
- Evaluation and decision is still ongoing



- Lower hitrate ( $< 10 \text{ MHz/cm}^2$ ) in oVTX
- Power consuming feature: PTD enabled in oVTX
- Extensive calibration for timewalk and gate-delays necessary

### • In standalone mode, one additional LVDS line per chip

- For 4 macropixel per chip operation, two chips can share this transmission line
- With only two macropixels, four chips can share one line
- The operation mode can be configured by different wiring with the same chip

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